



I. Greetings

Welcome to APWS 2024, the 11th Asia-Pacific Workshop on Widegap Semiconductors, to be held in Busan, South Korea, from October 13 to 17, 2024.

APWS is a biennial conference where researchers from the Asia-Pacific region come together to discuss and lead the way in the field of widegap and ultra-widegap semiconductors, such as III-nitrides, Silicon Carbides, Gallium Oxides, Diamonds, and h-BNs etc. It provides a platform for stimulating discussions and sharing ideas about widegap semiconductors, and it sets the pace for new developments in this field.

We strongly believe APWS 2024 will be an excellent opportunity for diverse regional and global researchers to engage in discussions and exchange ideas regarding widegap semiconductors. In particular, it is expected that sponsors will be highly satisfied with the exposure to participants.

We are planning to provide promotion opportunities through our website, program book, and other means. We hope that many companies will get the opportunity to enhance their brand image, promote their businesses, and expand their professional networks by participating as sponsors at APWS 2024.

We are honored to invite you to APWS 2024, where you will have the chance to be at the forefront of future developments in the field of widegap and ultra-widegap semiconductors. We look forward to meeting you in Busan in October 2024.

Thank you very much.

Sincerely,

Okhyun Nam (Tech Univ. of Korea, Korea)
On behalf of the APWS 2024 Organizing Committee



II. Outline

Conference Title	The 11th Asia-Pacific Workshop on Widegap Semiconductors		
Date	October 13 (Sun.) -17 (Thu.), 2024		
Location	Hanwha Resorts Haeundae, Busan, Korea		
Type	Face-to-face on-site course		
Attendees	350 Attendees (Expected)		
Programs	 Plenary Sessions Oral & Poster Sessions Excursion Banquet Exhibition 		
Organizer	Korea Society of LEDs and Optoelectronics (KSLOE)		
Homepage	www.apws2024.org		
Language	English		

III. Program

Oct. 13 (Sun.)	Oct. 14 (Mon.)	Oct. 15 (Tue.)	Oct. 16 (Wed.)	Oct. 17 (Thu.)	
Short Course Welcome Reception	Opening	Plenary Session	Oral Session	Poster Session	
	Plenary Session	Oral Session	Oral Session	r Oster Session	
	Lunch				
	Oral Session	Oral Session	Oral Session	Plenary Session	
	Oral Session	Oral Session	Banquet	Closing	



IV. Committee

Honorary chair & Co-chairs		
Hyung Jae Lee (Chair) Chonbuk Nat'l Univ., Korea		
Akihiko Yoshikawa	Chiba Univ., Japan	
Guoyi Zhang	Peking Univ., China	
Yan-Kuin Su	Kun Shan Univ., Taiwan	

Organizing committee	
Chair	
Okhyun Nam	Tech Univ. of Korea, Korea
Co-chairs	
Yoichi Kawakami	Kyoto Univ., Japan
Yao Hao	Xidian Univ., China
Jen-Inn Chyi	Nat'l Central Univ., Taiwan
Abdallah Ougazzaden	Georgia Tech Europe, France
Vice chairs	
Yong-Hoon Cho	KAIST, Korea
Dong-Seon Lee	GIST, Korea
Won-Jae Lee	Dongeui Univ., Korea
Jae Kyoung Mun	ETRI, Korea
Secretary	
Dae-Woo Jeon	KICET, Korea
Si-Young Bae	Pukyong Nat'l Univ., Korea



IV. Committee

Finance committee	
Chair	
Jong-Hyeob Baek (Chiar)	KOPTI, Korea
Co-chair	
Jin-Ki Kang	AXEL, Korea

Program committee		
Chair		
In-Hwan Lee	Korea Univ., Korea	
Co-chairs		
Symposium GL: III-N Materials	and Lighting Devices	
Kazuhiro Ohkawa	KAUST, Saudi Arabia	
Young Joon Hong	Sungkyunkwan Univ., Korea	
Symposium GE: III-N Materials	and Electronic Devices	
Kevin Chen	HKUST, Hong Kong	
Ho-Young Cha	Hongik Univ., Korea	
Symposium GaO: Ga ₂ O ₃ Materi	als and Electronic Devices	
Ray-Hua Horng	Nat'l Yang Ming Chiao Tung Univ., Taiwan	
Wan Sik Hwang	Korea Aerospace Univ., Korea	
Symposium SiC: SiC Materials and Devices		
Noboru Ohtani	Kwansei Gakuin Univ., Japan	
Seong-Min Jeong	KICET, Korea	



V. Sponsorship Information

We have a range of sponsorship packages designed to suit all your needs. Your sponsorship in this exciting event will provide excellent opportunities for your company to expose high quality products and services to the experts from all parts of the world. * All sponsorship categories are filled on a first-come, first-served basis.

| Application Procedure

- Please download the Sponsorship Application form, fill out and e-mail it to the APWS 2024 Secretariat (info@apws2024.org).
- All payments should be transferred to the bank account within 2 weeks of submitting the application.
- Please send the receipt to the secretariat for confirmation of full payment.

| Application Deadline

September 30 (Mon.), 2024

| Sponsorship Levels & Benefits

		Diamond	Platinum	Gold	Silver	Bronze
Category		KRW 10,000,000	KRW 7,000,000	KRW 5,000,000	KRW 3,000,000	KRW 1,000,000
Free Exhi	bition Booth	2	1	1	X	Х
Free Regi	stration	5	4	2	1	X
Advertise	Advertisement on the Program		1 Page	1 Page	½ Page	Х
	Program Book	0	0	0	0	0
Logo Printing	Banner at the Venue	0	0	0	0	Х
	Strap of the Name Badge	0	X	Х	Х	Х
Web	Website Main Page	0	0	0	0	0
Banner (Logo + Link)	Website Sponsor Page	0	0	0	0	0
	Webmail Newsletter	0	0	0	х	Х
Play the Promotion Video during Session Break Time		0	0	Х	Х	Х



| Booth Information

- APWS 2024 exhibition is only available as part of the sponsorship benefits.
- Due to limited exhibition spaces, free booths are provided on a first-come, first-served basis, and if fully booked, free registration is provided.

EXHIBITION BOOTH TYPE(2X2)





X Shell Scheme Package (Per One Booth)

- Size: 2m(W) *2m(L) *2.5m(H)
- 1 information desk / 2 chairs
- Lighting and 1KW of power



Sponsorship Application Form

Please fill out the below application form, and send it back to the secretariat.

APWS 2024 Secretariat

E-mail: info@apws2024.org / Tel: +82-42-472-7460 / Fax: +82-42-472-7459

| Company Information

Company Name		
President Name		
Website		
Address		
City / Country	Postal Code	
Telephone	Mobile	
E-mail	Fax	
Contact Person Name		
Job Title	Department	

| Sponsorship

Level	KRW	Apply (Check "O")
Diamond	KRW 10,000,000	
Platinum	KRW 7,000,000	
Gold	KRW 5,000,000	
Silver	KRW 3,000,000	
Bronze	KRW 1,000,000	

| Account Information

Bank Name	SHINHAN BANK
Account Holder	사단법인 한국엘이디광전자학회 (Korea Society of LEDs and Optoelectronics)
Account Number	100-035-605475
Swift BIC	SHBKKRSE
Bank Address	20, SEJONG-DAERO 9-GIL, JOUNG-GU, SEOUL, SOUTH KOREA

Name of Applicant:	Date:	
	Signature:	